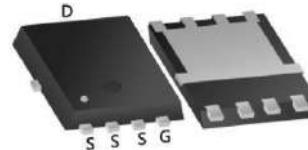


N-Ch 60V Fast Switching MOSFETs

Features:

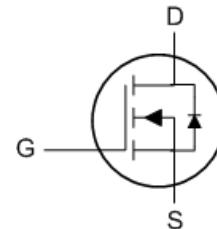
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology



PRPAK3X3 Pin Configuration

Description:

The KSPRB6016 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications. The KSPRB6016 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.



Product Summary

BVDSS	RDS(on)	ID
60V	12mΩ	44A

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	60	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _c =25°C	Continuous Drain Current ¹	44	A
I _D @T _c =100°C	Continuous Drain Current ¹	28	A
I _{DM}	Pulsed Drain Current ²	100	A
EAS	Single Pulse Avalanche Energy ³	72.2	mJ
I _{AS}	Avalanche Current	38	A
P _D @T _c =25°C	Total Power Dissipation ⁴	42	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	75	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	3	°C/W

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=250\mu\text{A}$	60	---	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=10\text{V}$, $I_{\text{D}}=8\text{A}$	---	---	12	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_{\text{D}}=6\text{A}$	---	---	15	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_{\text{D}}=250\mu\text{A}$	1.2	---	2.5	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=48\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^{\circ}\text{C}$	---	---	1	uA
		$V_{\text{DS}}=48\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^{\circ}\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{\text{DS}}=5\text{V}$, $I_{\text{D}}=8\text{A}$	---	75	---	S
R_g	Gate Resistance	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	1.5	---	Ω
Q_{g}	Total Gate Charge (4.5V)	$V_{\text{DS}}=30\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_{\text{D}}=8\text{A}$	---	28.7	---	nC
Q_{gs}	Gate-Source Charge		---	10.5	---	
Q_{gd}	Gate-Drain Charge		---	9.9	---	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=30\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_{\text{G}}=3.3\Omega$, $I_{\text{D}}=8\text{A}$	---	10.4	---	ns
T_r	Rise Time		---	9.2	---	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	63	---	
T_f	Fall Time		---	4.8	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	3240	---	pF
C_{oss}	Output Capacitance		---	210	---	
C_{rss}	Reverse Transfer Capacitance		---	146	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_{s}	Continuous Source Current ^{1,5}	$V_{\text{G}}=V_{\text{D}}=0\text{V}$, Force Current	---	---	44	A
I_{sm}	Pulsed Source Current ^{2,5}		---	---	100	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $\text{I}_{\text{s}}=\text{A}$, $T_J=25^{\circ}\text{C}$	---	---	1.2	V
t_{rr}	Reverse Recovery Time	$\text{I}_{\text{F}}=8\text{A}$, $d\text{I}/dt=100\text{A}/\mu\text{s}$,	---	18	---	nS
		$T_J=25^{\circ}\text{C}$	---	14	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $\text{I}_{\text{AS}}=38\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_{D} and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

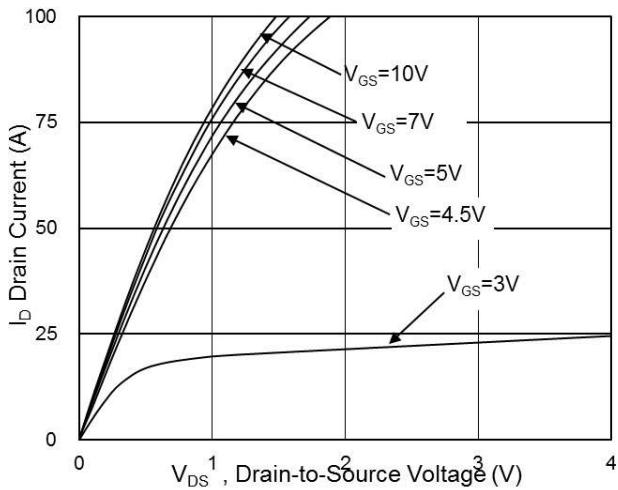


Fig.1 Typical Output Characteristics

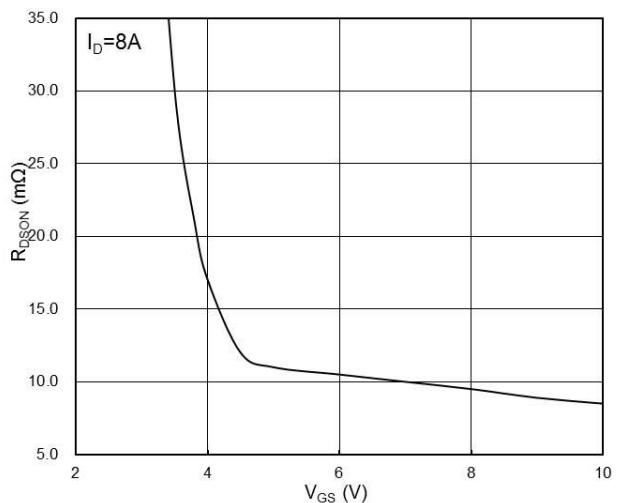


Fig.2 On-Resistance vs. Gate-Source Voltage

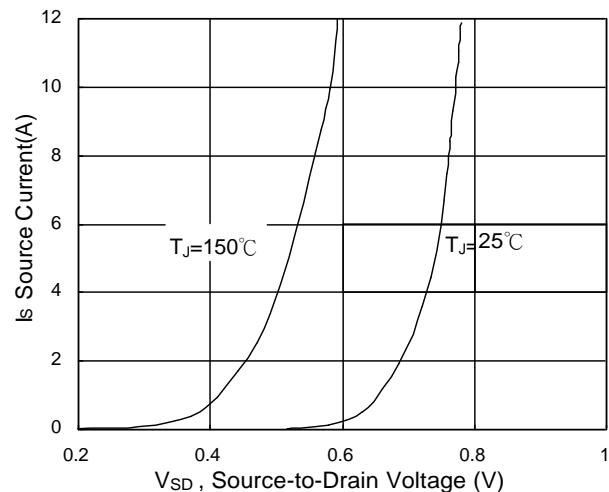


Fig.3 Forward Characteristics of Reverse

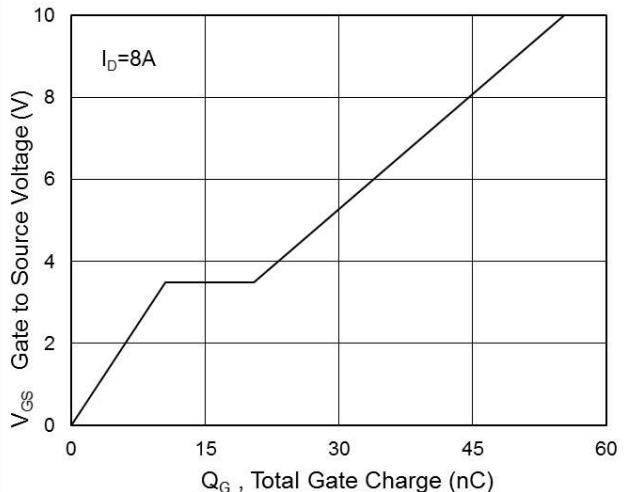


Fig.4 Gate-Charge Characteristics

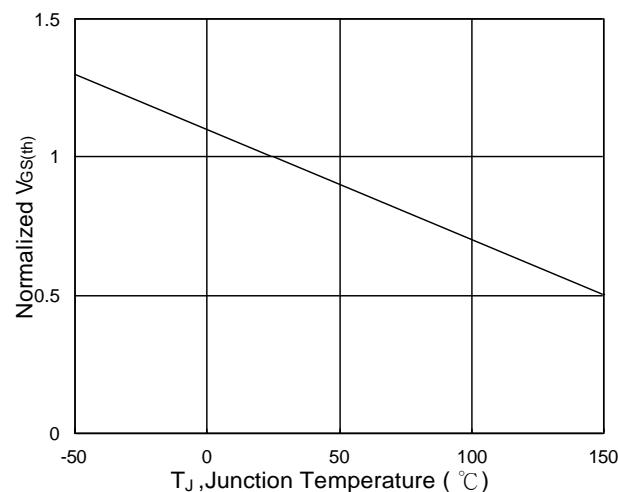


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

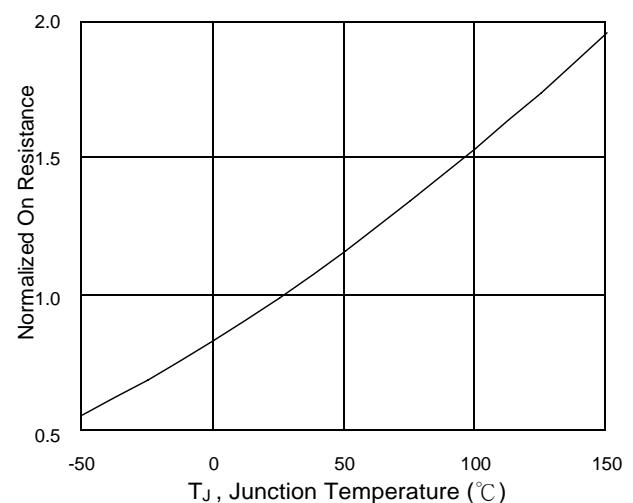


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

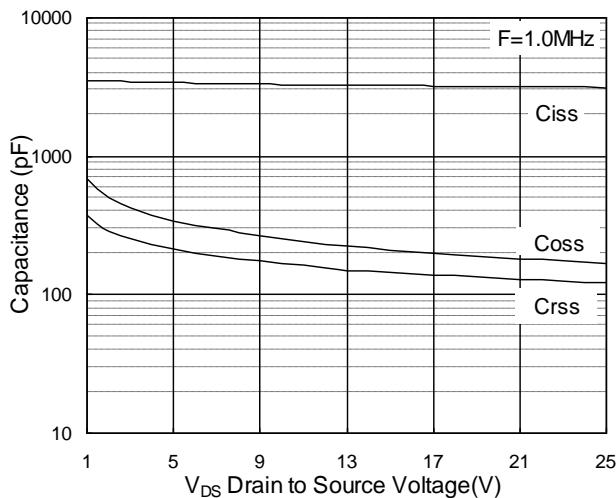


Fig.7 Capacitance

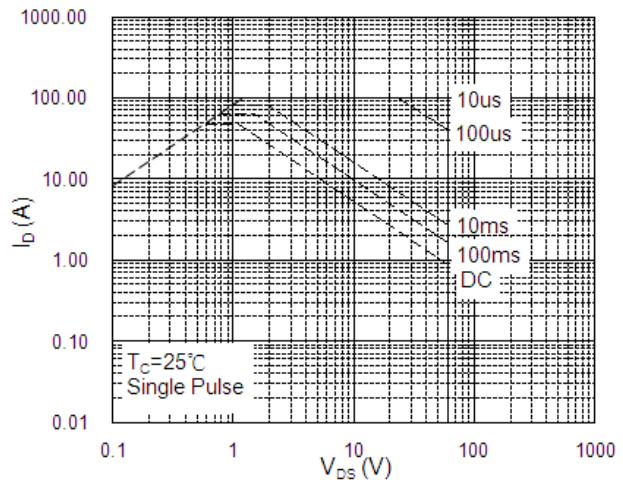


Fig.8 Safe Operating Area

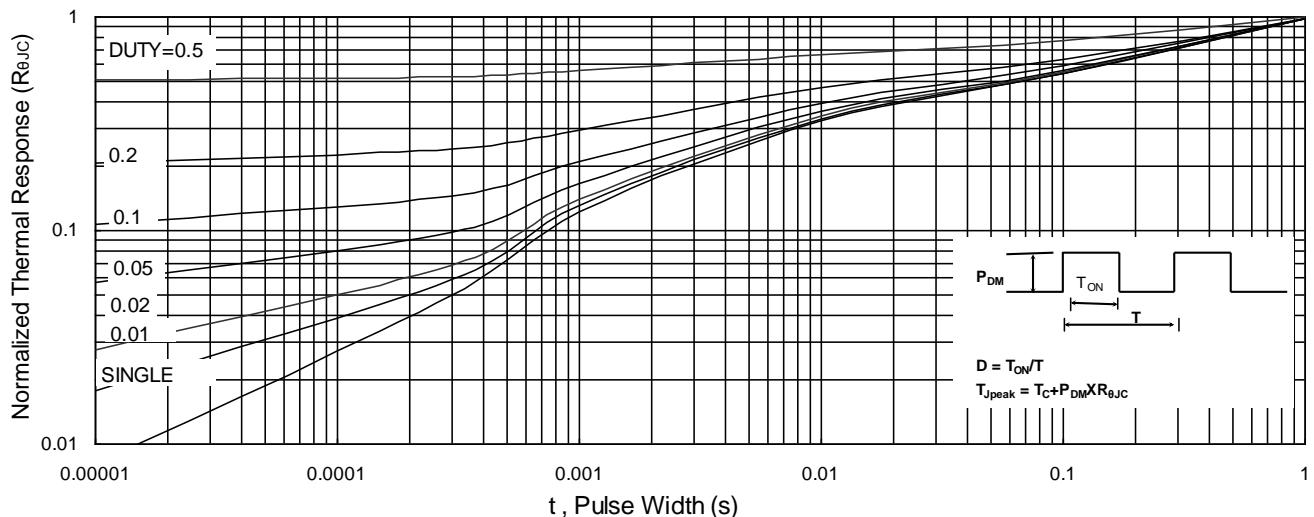


Fig.9 Normalized Maximum Transient Thermal Impedance

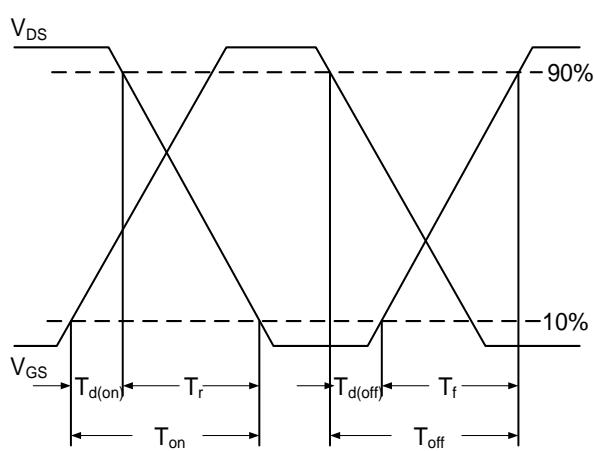


Fig.10 Switching Time Waveform

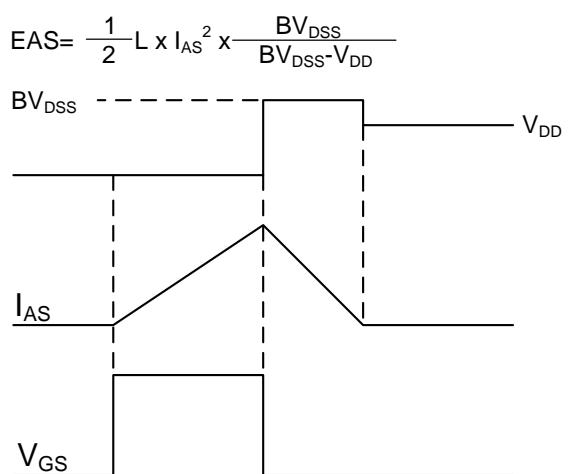


Fig.11 Unclamped Inductive Switching Waveform